12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20131218001
Qualification of Alternate Assembly site for select WCSP devices
Change Notification / Sample Request

Date: 12/30/2013
To: Digi-Key PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20131218001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TCA6418EYFPR	null
TCA8418EYFPR	null
TPS22921YZPR	null
TPS22946YZPR	null
TPS22906YZVR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20131218001	**PCN Date:**	12/30/2013

Title:	Qualification of Alternate Assembly site for select WCSP devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	03/30/2014	**Estimated Sample Availability:**	12/30/2013

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of JCAP as an alternate assembly site for the devices listed below. There is no material or dimensional differences between devices assembled at the 2 sites.

Reason for Change:

Continuity of Supply

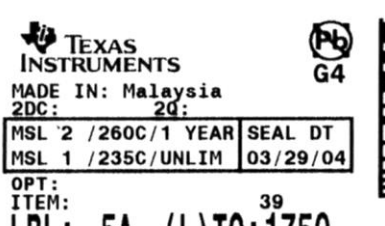
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
STATS ChipPAC (SCS)	Assembly Site Origin (22L)	ASO: STS
JCAP	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS

Topside Device marking:
Assembly site code for STS= G
Assembly site code for JCP= P

Product Affected

TCA6418EYFPR	TCA8418EYFPR	TPS22906YZVR	TPS22921YZPR
TPS22946YZPR			

Qualification Data: (Approved: June 2009)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: CD3239 (MSL 1-260C)

Package / Die Attributes

Assembly Site & Bump Site:	JCAP	Bump Composition:	SnAgCu
# Pins-Designator, Family:	25-YFP, DSBGA	Bump Diameter:	0.23mm
Passivation/Coating:	MA21009085		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail Lot#1	Lot#2	Lot#3
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	115/0	116/0
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	121C (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-55C/+125C (500, 1000 Cyc)	77/0	77/0	77/0
Visual Mechanical	Per Manufacturing Specifications	Pass	Pass	Pass
Physical Dimensions	(per mechanical drawing)	Pass	Pass	Pass
**Preconditioning: MSL1@260C				

Reference Qualification Data: (Approved: June 2010)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TPS22934YZVR (MSL 1-260C)

Package Construction Details

Assembly Site & Bump Site:	JCAP	Bump Composition:	SnAgCu
# Pins-Designator, Family:	4-YZV, DSBGA	Bump Diameter:	0.225mm
Passivation/Coating:	MA21009085		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Visual Mechanical	Per Manufacturing Specifications	Pass
Physical Dimensions	(per mechanical drawing)	Pass
Bump-shear	(per mfg. Site specification)	Pass
Notes: **Tests require preconditioning sequence: MSL1-260C		

Reference Qualification Data: (Approved: April 2008)					
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.					
Qualification Device: TS3DS26227YZT (MSL 1-260C)					
Package / Die Attributes					
Assembly Site & Bump Site:	JCAP	Bump Composition:	SnAgCu		
# Pins-Designator, Family:	12-YZT, DSBGA	Bump Diameter:	0.225mm		
Passivation/Coating:	MA21009085				
Qualification: ☐ **Plan** ☒ **Test Results**					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	116/0	116/0	
**High Temp. Storage Bake	170C (168, 420hrs)	77/0	77/0	77/0	
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0	
**T/C -55C/125C	-55C/+125C (500, 1000 Cyc)	77/0	77/0	77/0	
Visual Mechanical	Per Manufacturing Specifications	Pass	Pass	Pass	
Solderability	Steam age, 8 hours	Pass	Pass	Pass	
Physical Dimensions	(per mechanical drawing)	Pass	Pass	Pass	
Bump-shear	(per mfg. Site specification)	Pass	Pass	Pass	
**Preconditioning: MSL1@260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com